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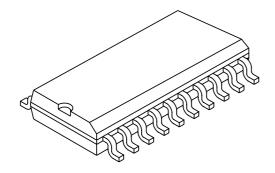
If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

# **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# **BZA100**18-fold ESD transient voltage suppressor

Product data sheet Supersedes data of 1996 Mar 21 1997 Dec 02



# 18-fold ESD transient voltage suppressor

**BZA100** 

### **FEATURES**

- SO20 SMD package allows 18 separate voltage regulator diodes in a common anode configuration
- Working voltage: typ. 6.8 V
- Forward voltage: max. 1.3 V
- Maximum reverse peak power dissipation: 27.5 W at t<sub>p</sub> = 1 ms
- Maximum clamping voltage at peak pulse current: 11 V at 2.5 A
- Low leakage current: max. 2 μA
- ESD rating >8 kV, according IEC 801-2.

# **APPLICATIONS**

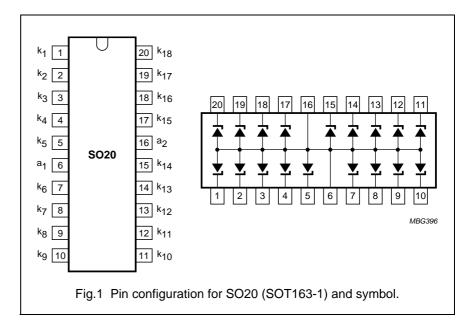
- Where transient overvoltage protection in voltage and ESD sensitive equipment is required such as:
  - Computers
  - Printers
  - Business machines
  - Communication systems
  - Medical equipment.

## DESCRIPTION

18-fold monolitic transient voltage suppressor. Its 18-fold junction common anode design protects 18 separate lines using only one package. This device is ideal for situations where board space is a premium.

### **PINNING**

PIN	DESCRIPTION
1 to 5	cathode (k <sub>1</sub> to k <sub>5</sub> )
6 and 16	common anode (a <sub>1</sub> ; a <sub>2</sub> )
7 to 15	cathode (k <sub>6</sub> to k <sub>14</sub> )
17 to 20	cathode (k <sub>15</sub> to k <sub>18</sub> )



# **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>Z</sub>	working current		_	note 1	mA
I <sub>F</sub>	continuous forward current		_	200	mA
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> = 1 ms; square pulse	-	4	Α
I <sub>ZSM</sub>	non-repetitive peak reverse current	t <sub>p</sub> = 1 ms; square pulse; see Fig.2	_	2.5	Α
P <sub>tot</sub>	total power dissipation	see Fig.3			
		up to $T_s = 60 ^{\circ}\text{C}$ ; note 2	_	1.6	W
		up to T <sub>amb</sub> = 25 °C; note 3	_	1.25	W
P <sub>ZSM</sub>	non-repetitive peak reverse power dissipation	t <sub>p</sub> = 1 ms; square pulse; see Fig.4	_	27.5	W
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	operating junction temperature		_	150	°C

# Notes

- 1. DC working current limited by Ptot max.
- One or more diodes loaded; T<sub>s</sub> is the temperature at the soldering point.
- 3. One or more diodes loaded; device mounted on a printed-circuit board with R<sub>th a-s</sub> = 43.5 K/W.

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BZA100

# THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-s</sub>	thermal resistance from junction to soldering point	one or more diodes loaded	56.5	K/W
R <sub>th j-a</sub>	thermal resistance from junction to ambient		100	K/W

# **ELECTRICAL CHARACTERISTICS**

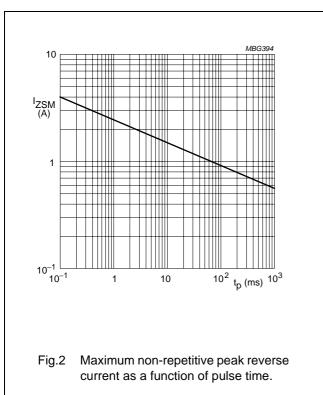
 $T_i = 25$  °C unless otherwise specified.

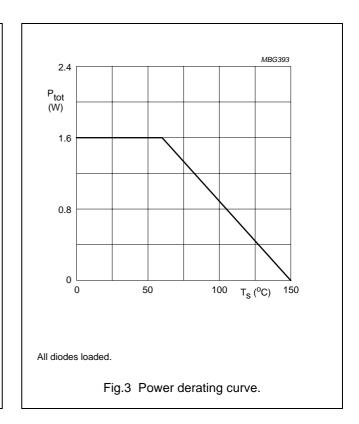
SYMBOL	PARAMETER	PARAMETER CONDITIONS MIN.				UNIT
Per diode						
Vz	working voltage	working voltage $I_Z = 5 \text{ mA}$ 6.4		6.8	7.2	V
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 200 mA	_	_	1.3	V
V <sub>ZSM</sub>	non-repetitive peak reverse voltage	$t_p = 1 \text{ ms}; I_{ZSM} = 2.5 \text{ A}$	_	_	11	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 5.25 V	_	_	2	μΑ
r <sub>dif</sub>	differential resistance	$I_Z = 1 \text{ mA}$	_	_	40	Ω
		$I_Z = 5 \text{ mA}$	_	_	8	Ω
Sz	temperature coefficient of working voltage	$I_Z = 5mA$	_	3	_	mV/K
C <sub>d</sub>	diode capacitance	see Fig.5				
		$V_R = 0; f = 1 MHz$	_	_	120	pF
		V <sub>R</sub> = 5.25 V; f = 1 MHz	_	_	60	pF

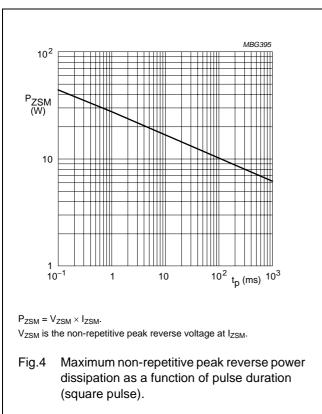
# 18-fold ESD transient voltage suppressor

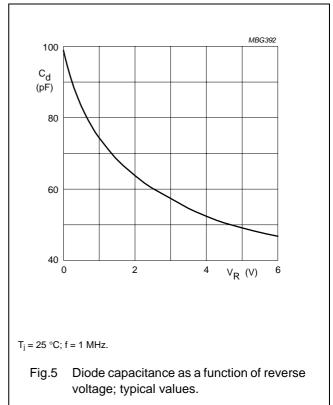
**BZA100** 

# **GRAPHICAL DATA**









1997 Dec 02

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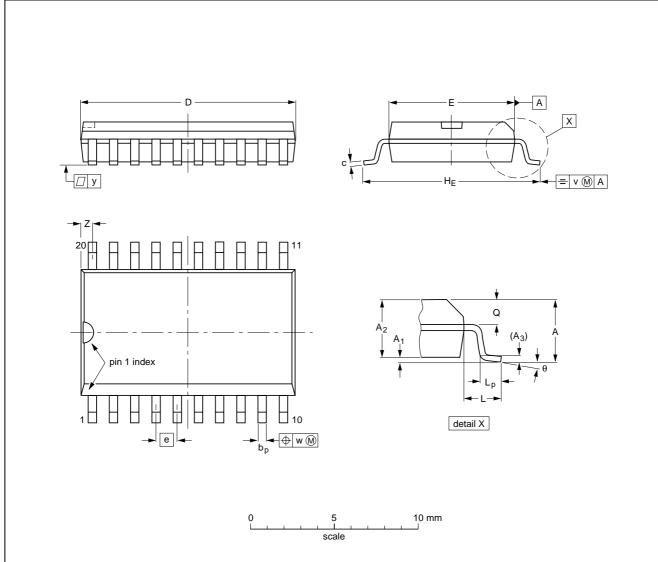
# 18-fold ESD transient voltage suppressor

**BZA100** 

# **PACKAGE OUTLINE**

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



# DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	z <sup>(1)</sup>	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

# Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE	NE REFERENCES					ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	
SOT163-1	075E04	MS-013				<del>-99-12-27</del> 03-02-19

# 18-fold ESD transient voltage suppressor

**BZA100** 

### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

### **Notes**

- 1. Please consult the most recently issued document before initiating or completing a design.
- 2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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# **NXP Semiconductors**

# **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

# **Contact information**

For additional information please visit: http://www.nxp.com
For sales offices addresses send e-mail to: salesaddresses@nxp.com

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